

Title

Please amend the title to read as follows:

METHODS FOR USING BI-MODAL ABRASIVE SLURRIES FOR MECHANICAL
AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-
DEVICE SUBSTRATE ASSEMBLIES

In the Specification:

Amend the specification by inserting a new section before the "Technical Field"
as follows:

-- CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a divisional of pending United States Patent Application No. 10/155,203, filed May 23, 2002, which application is a continuation of United States Patent Application No. 09/289,790, filed April 9, 1999, which issued as United States Patent No. 6,407,000. --